

General Description

- Latest Trench Power LV technology
- Very Low $R_{DS(on)}$ at 4.5V_{GS}
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

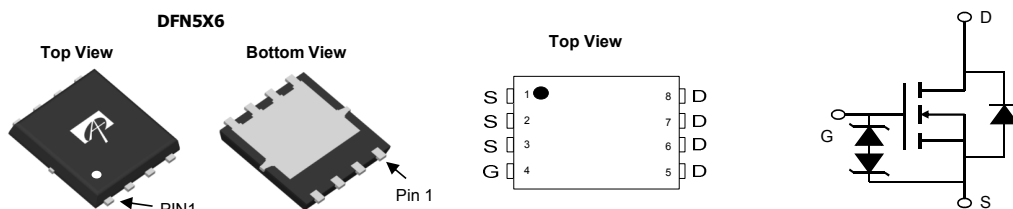
Application

- DC/DC Converters in Computing, Servers, and POL
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

V_{DS}	30V
I_D (at $V_{GS}=10V$)	170A
$R_{DS(on)}$ (at $V_{GS}=10V$)	< 2.3m Ω
$R_{DS(on)}$ (at $V_{GS}=4.5V$)	< 3.5m Ω

ESD protected
 100% UIS Tested
 100% R_g Tested



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^G	I_D	$T_C=25^\circ\text{C}$	170
		$T_C=100^\circ\text{C}$	110
Pulsed Drain Current ^C	I_{DM}	280	A
Continuous Drain Current	I_{DSM}	$T_A=25^\circ\text{C}$	25
		$T_A=70^\circ\text{C}$	19
Avalanche Current ^C	I_{AS}	60	A
Avalanche energy $L=0.1\text{mH}$ ^C	E_{AS}	180	mJ
Power Dissipation ^B	P_D	$T_C=25^\circ\text{C}$	110
		$T_C=100^\circ\text{C}$	45
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ\text{C}$	2.3
		$T_A=70^\circ\text{C}$	1.4
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	14	17	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Ambient ^{A,D}		40	55	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Case	$R_{\theta JC}$	0.85	1.1	$^\circ\text{C}/\text{W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30	36		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±16V			10	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	1.3	1.8	2.4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A T _J =125°C		1.9	2.3	mΩ
		V _{GS} =4.5V, I _D =20A		2.8	3.4	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		130		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.67	1	V
I _S	Maximum Body-Diode Continuous Current ^G				170	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		4300	5200	pF
C _{oss}	Output Capacitance			720		pF
C _{rss}	Reverse Transfer Capacitance			420		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	1	2	3	Ω
SWITCHING PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =20A		70	100	nC
Q _g (4.5V)	Total Gate Charge			33		nC
Q _{gs}	Gate Source Charge			10		nC
Q _{gd}	Gate Drain Charge			15		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =0.75Ω, R _{GEN} =3Ω		10		ns
t _r	Turn-On Rise Time			6.5		ns
t _{D(off)}	Turn-Off DelayTime			75		ns
t _f	Turn-Off Fall Time			18		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=500A/μs		30		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, dI/dt=500A/μs		15		nC

- A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 150° C may be used if the PCB allows it.
- B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.
- D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.
- G. The maximum current rating is package limited.
- H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

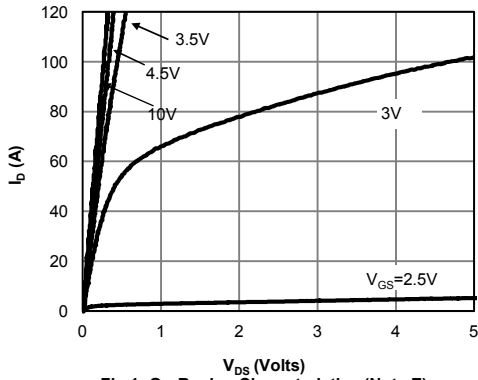


Figure 1: On-Region Characteristics (Note E)

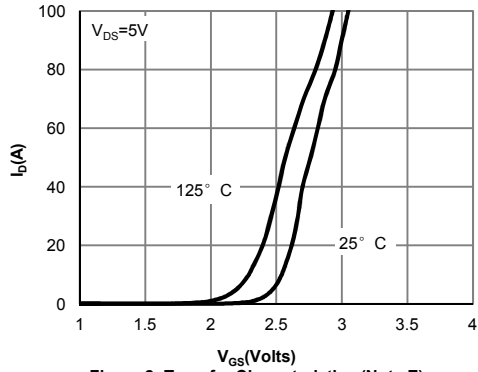


Figure 2: Transfer Characteristics (Note E)

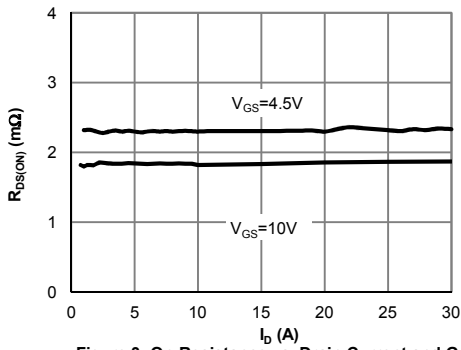


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

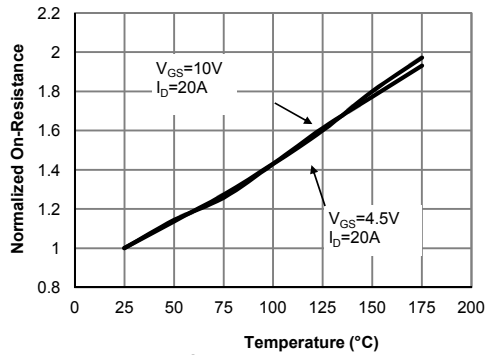


Figure 4: On-Resistance vs. Junction Temperature (Note E)

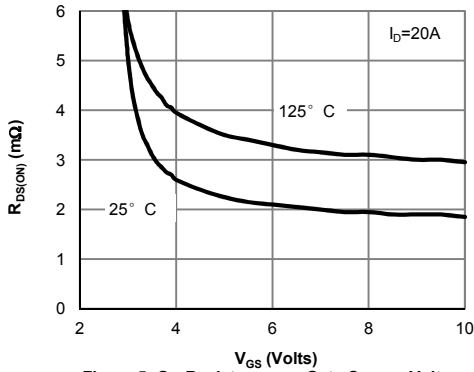


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

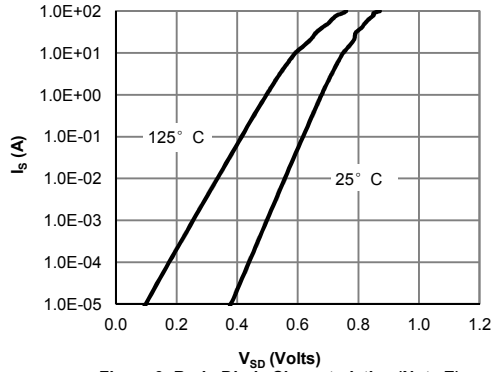
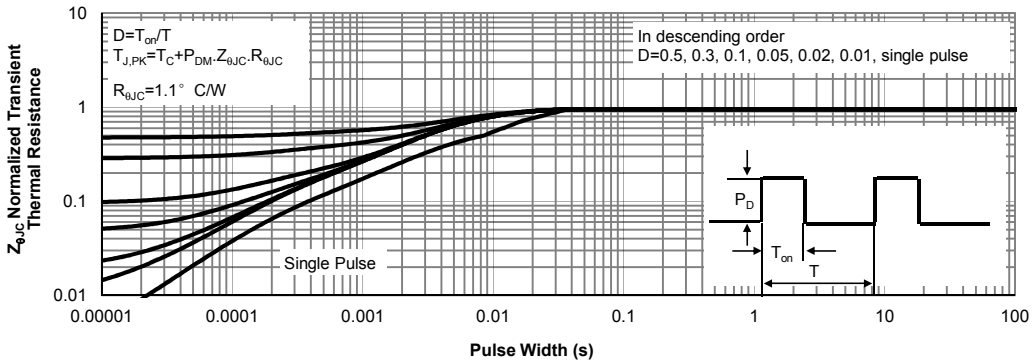
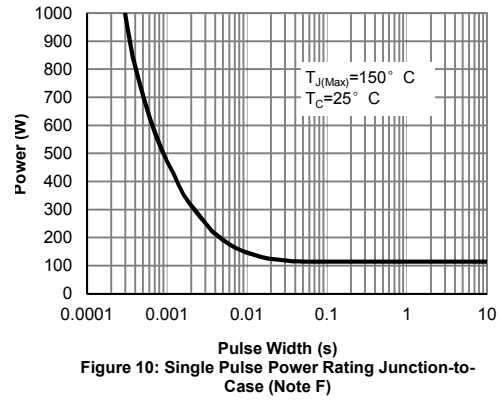
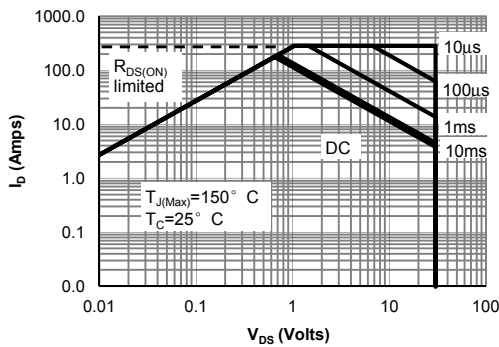
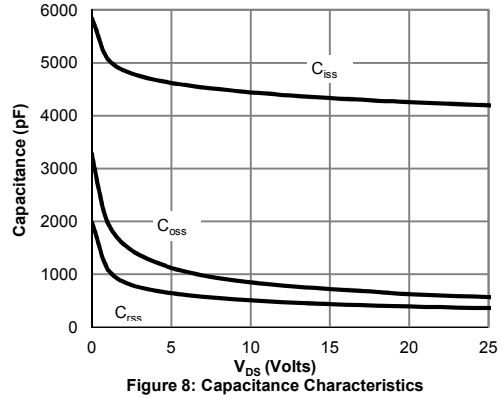
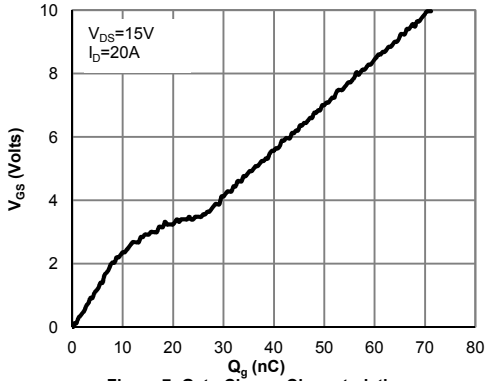


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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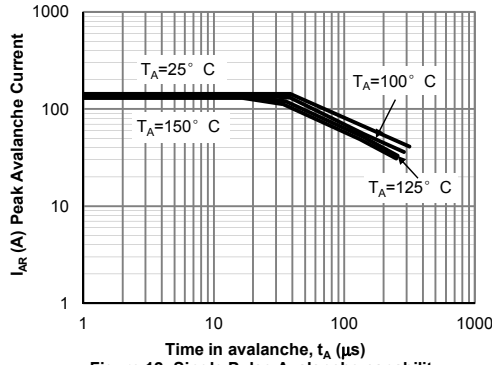


Figure 12: Single Pulse Avalanche capability (Note C)

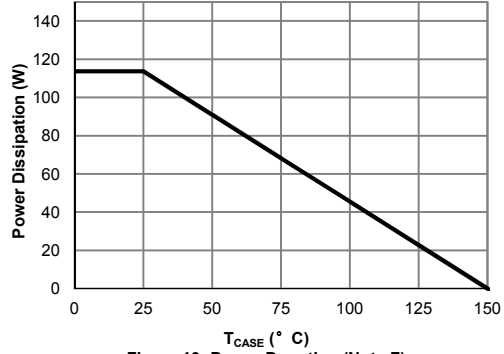


Figure 13: Power De-rating (Note F)

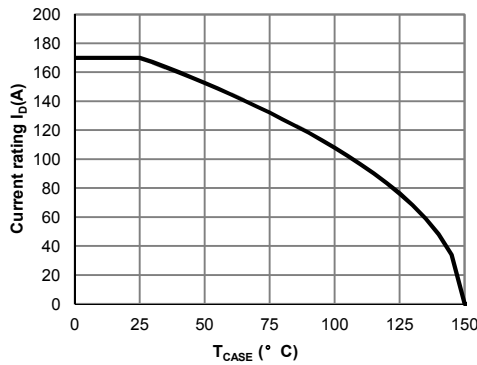


Figure 14: Current De-rating (Note F)

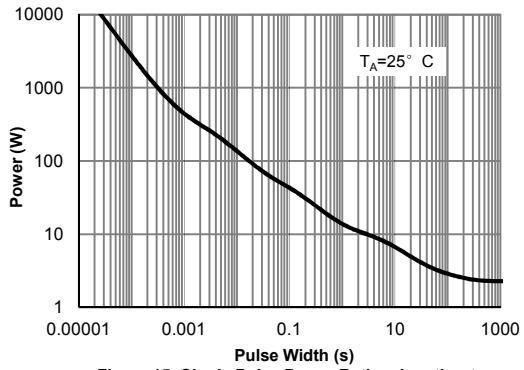


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

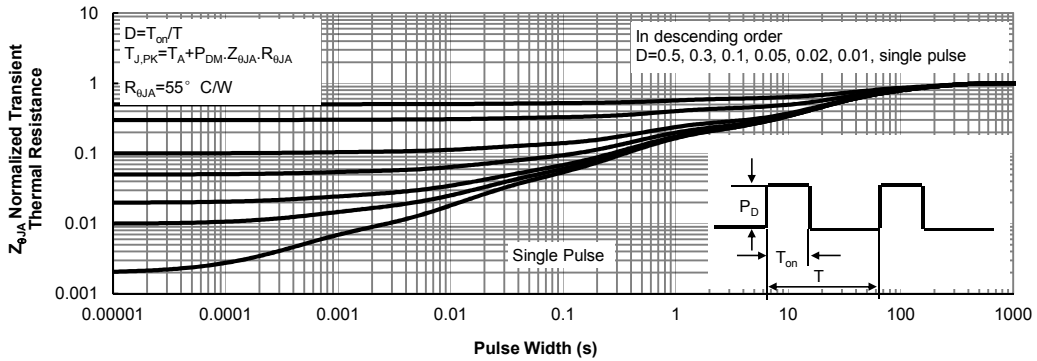
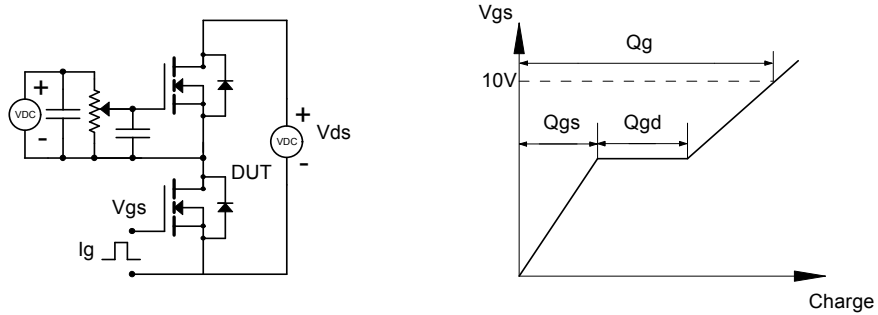
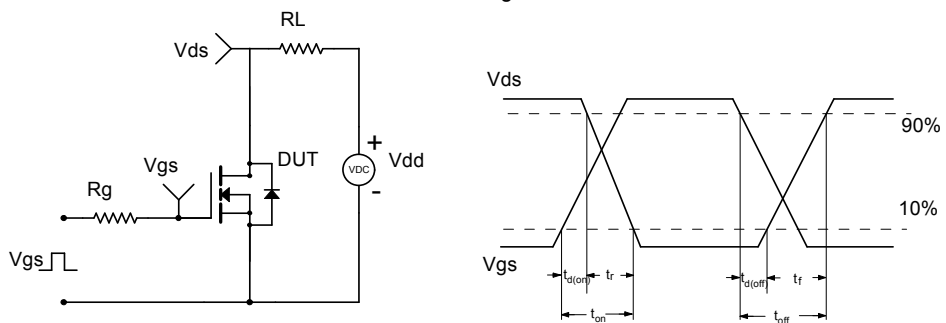


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

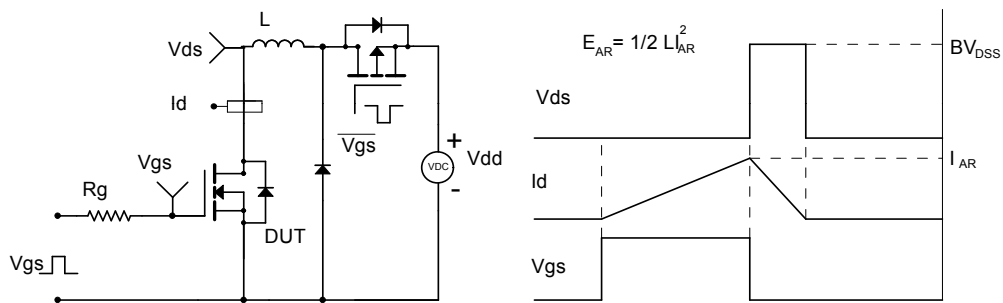
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

